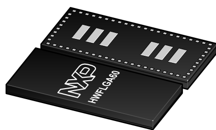

# SOT2168-1

## HWFLGA60, thermal enhanced very very thin finepitch land grid array package, 0.4 mm pitch, 9.05 mm x 4.05 mm x 0.63 mm body

15 November 2022 Package information

## 1 Package summary

| | |
|---|---|
| **Terminal position code** | B (bottom) |
| **Package type descriptive code** | HWFLGA60 |
| **Package style descriptive code** | HWFLGA (thermal enhanced land grid array package) |
| **Package body material type** | P (plastic) |
| **Mounting method type** | S (surface mount) |
| **Issue date** | 31-10-2022 |
| **Manufacturer package code** | 98ASA01867D |

Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|---|---|---|---|---|
| package length | - | 9.05 | - | mm |
| package width | - | 4.05 | - | mm |
| seated height | - | 0.63 | 0.687 | mm |
| nominal pitch | - | 0.4 | - | mm |
| actual quantity of termination | - | 60 | - | |

## 2 Package outline

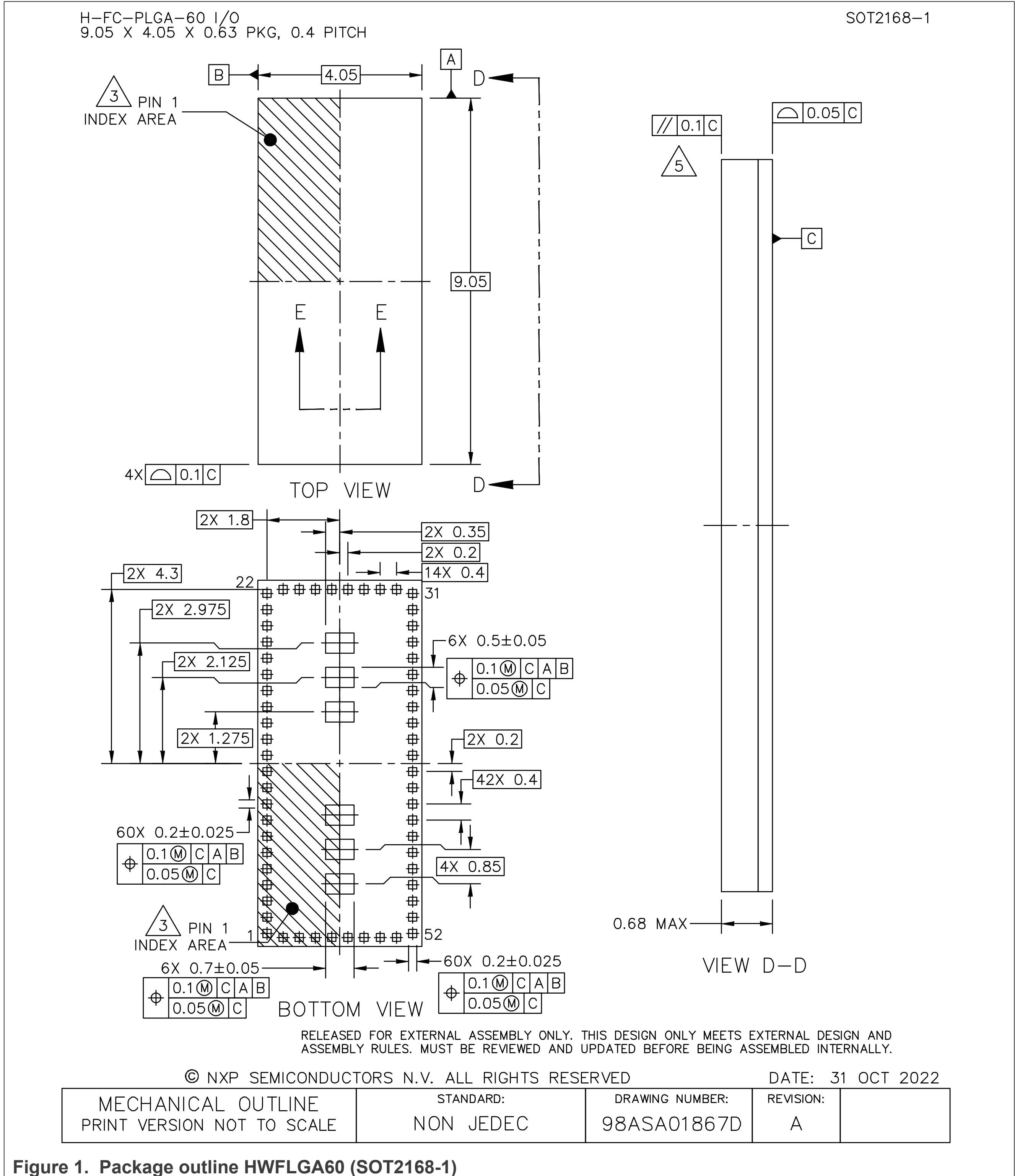


**Figure 1. Package outline HWFLGA60 (SOT2168-1)**

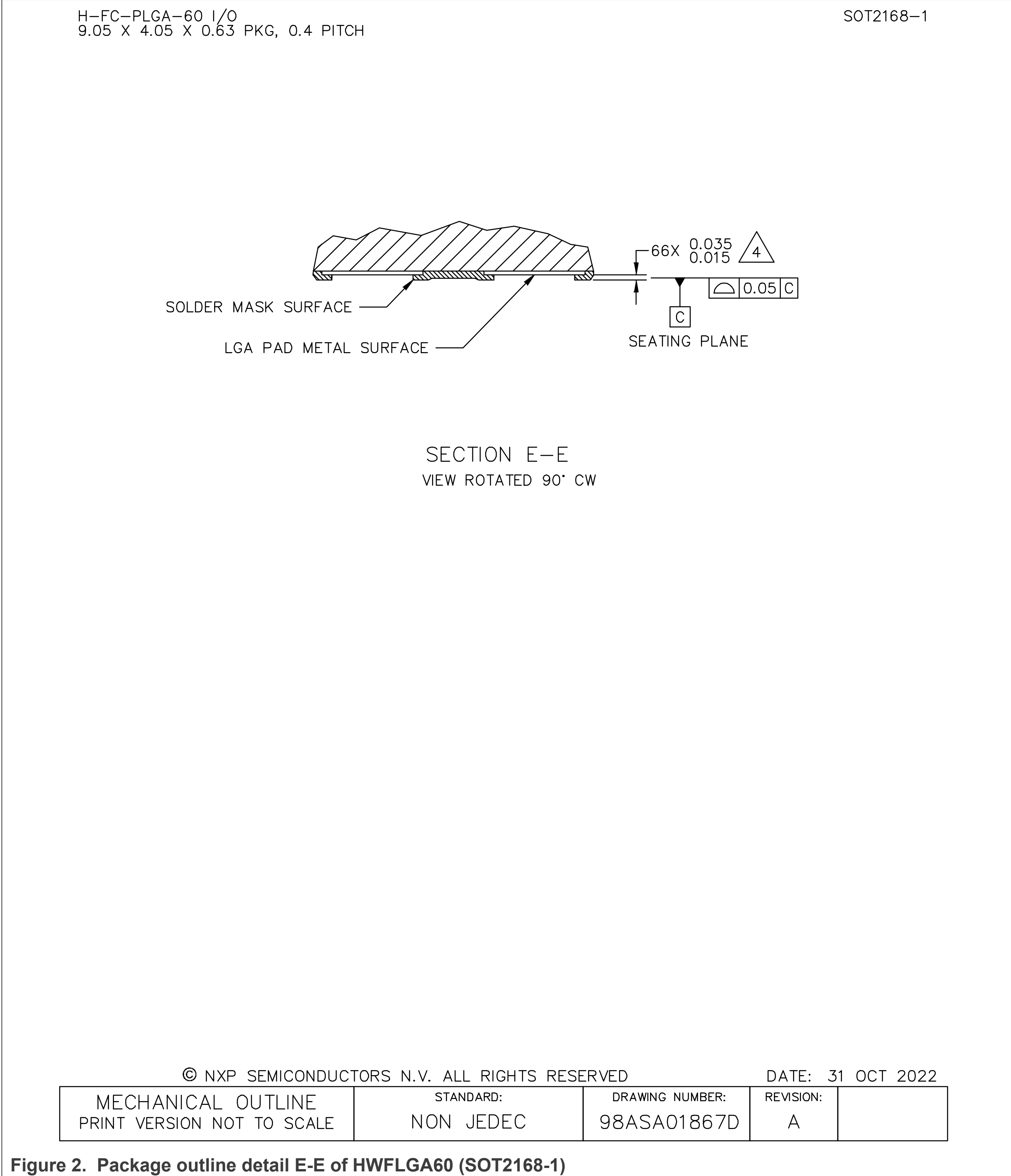


Figure 2. Package outline detail E-E of HWFLGA60 (SOT2168-1)


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# 3 Soldering

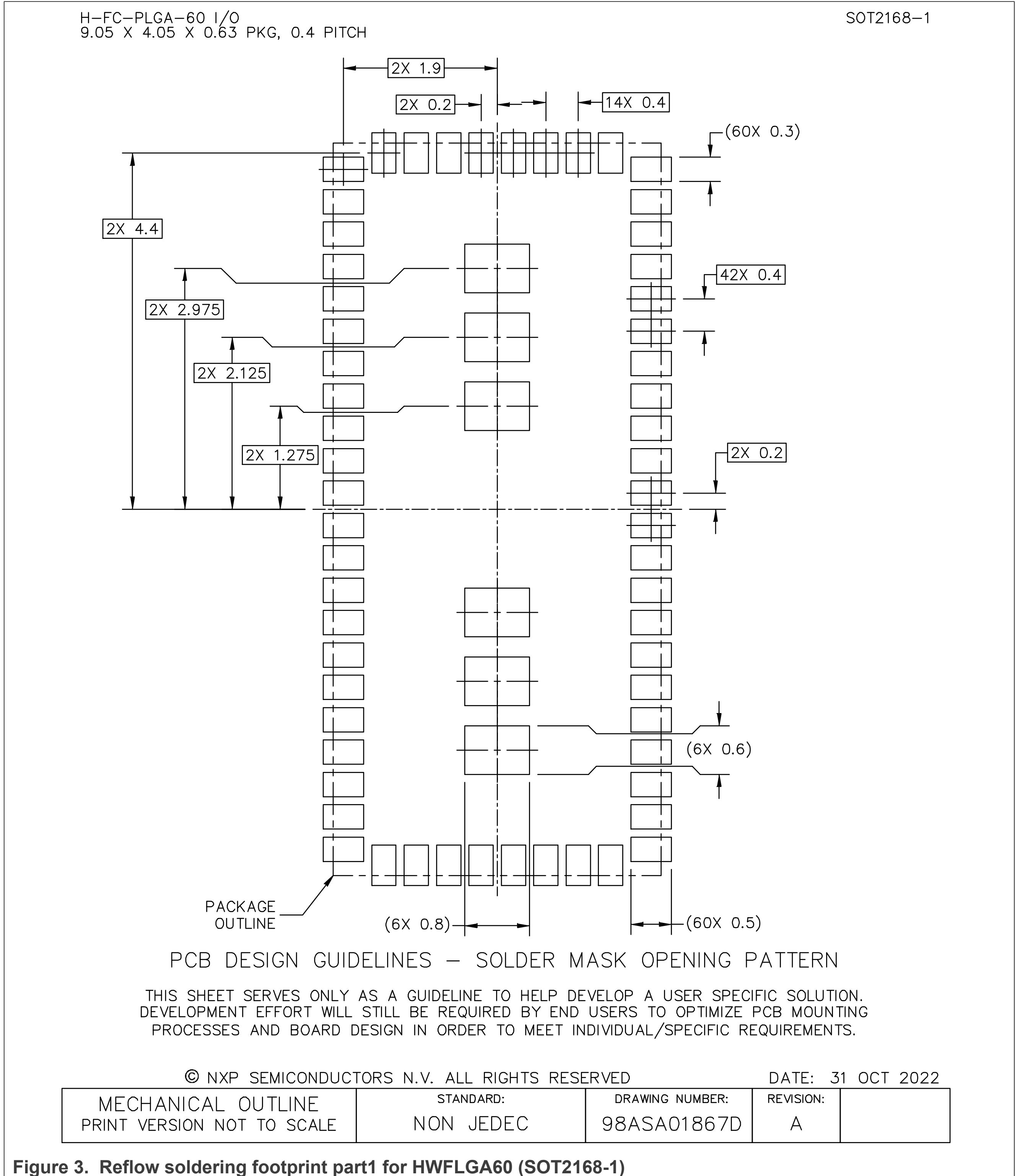


**Figure 3. Reflow soldering footprint part1 for HWFLGA60 (SOT2168-1)**



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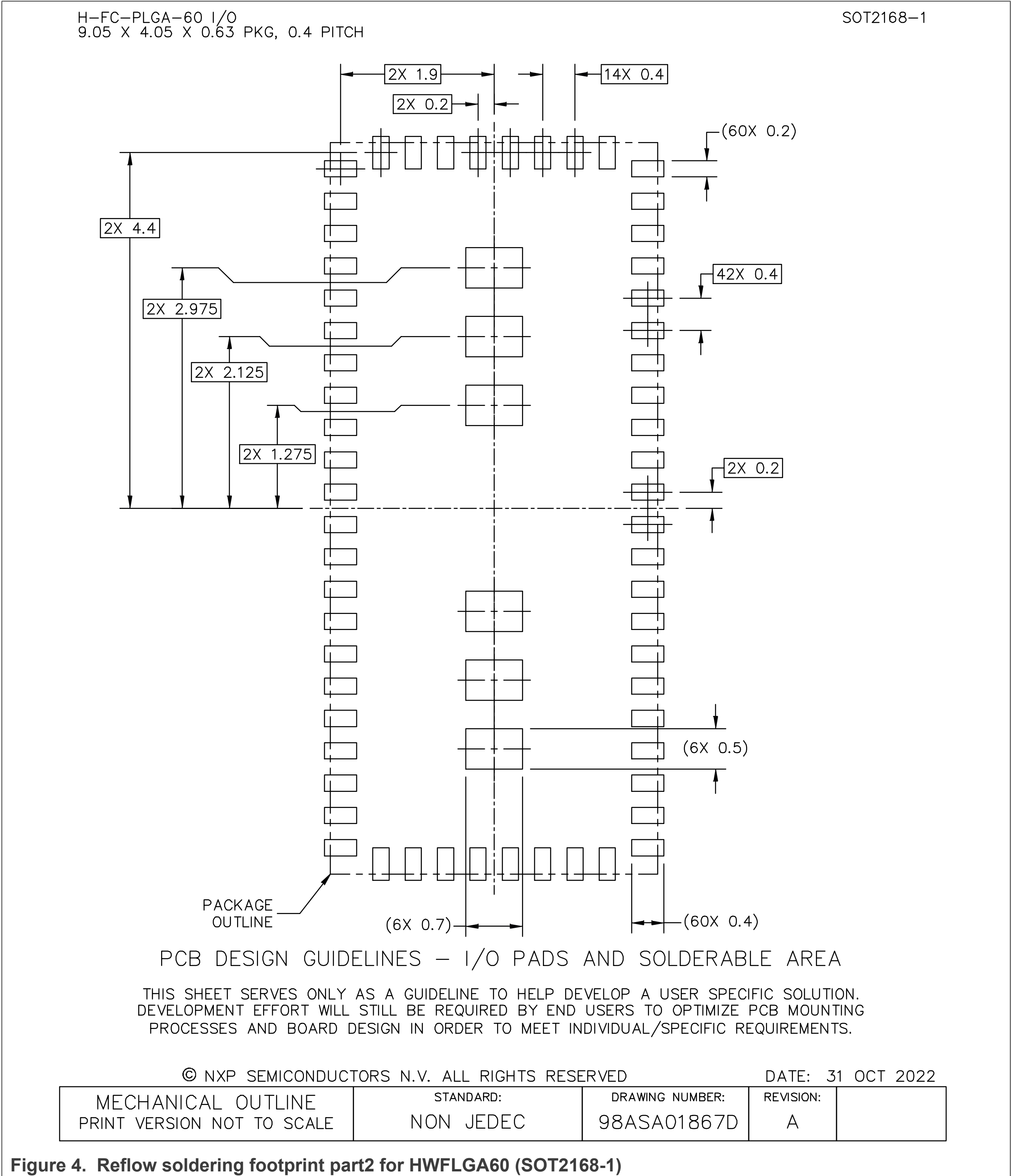


Figure 4. Reflow soldering footprint part2 for HWFLGA60 (SOT2168-1)


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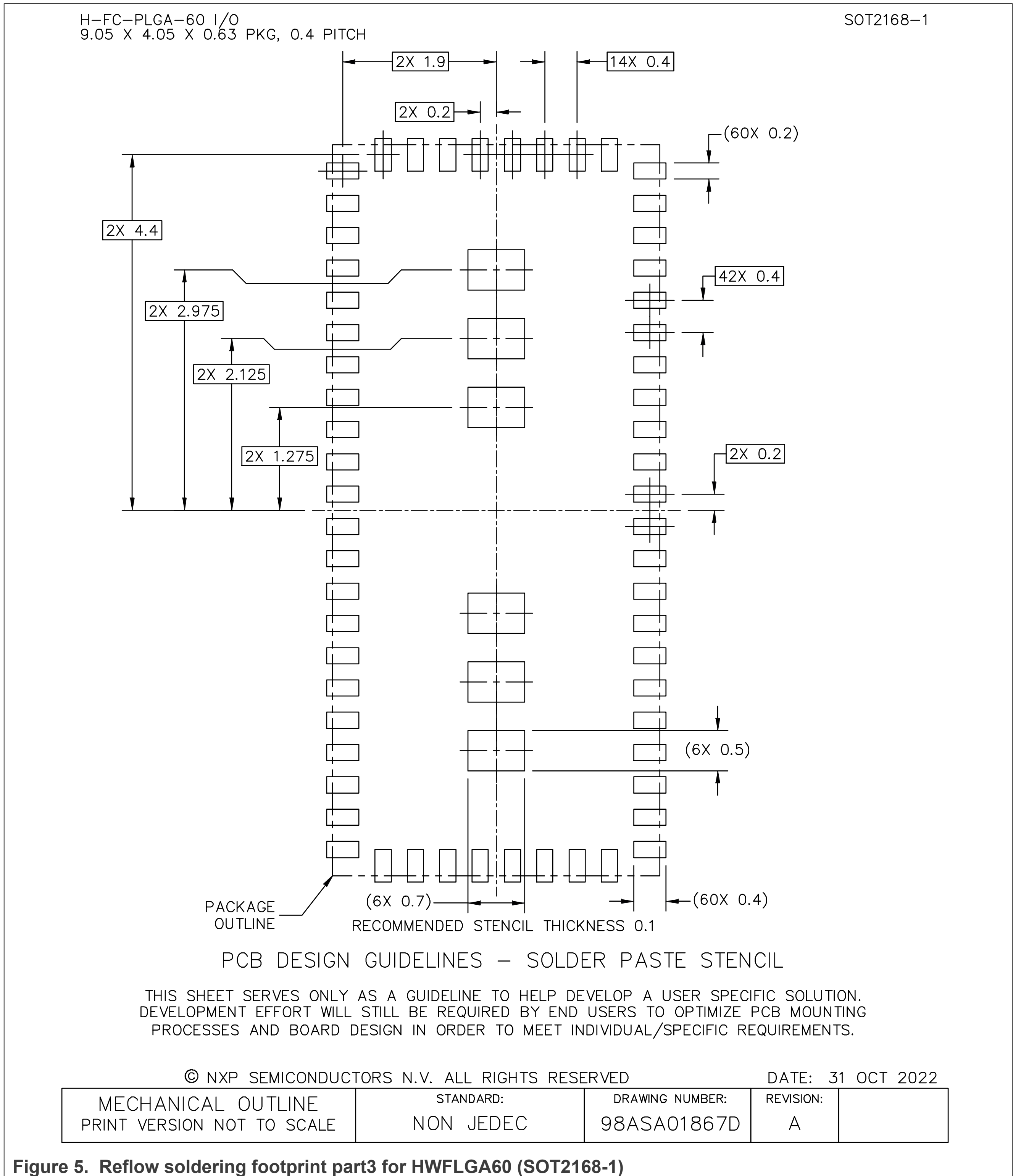


Figure 5. Reflow soldering footprint part3 for HWFLGA60 (SOT2168-1)



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H-FC-PLGA-60 I/O
9.05 X 4.05 X 0.63 PKG, 0.4 PITCH

SOT2168-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.

4. DIMENSION APPLIES TO ALL LEADS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE

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DATE: 31 OCT 2022

| MECHANICAL OUTLINE<br>PRINT VERSION NOT TO SCALE | STANDARD:<br>NON JEDEC | DRAWING NUMBER:<br>98ASA01867D | REVISION:<br>A | |
|---|---|---|---|---|

Figure 6. Package outline note HWFLGA60 (SOT2168-1)



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# 4 Legal information

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Date of release: 15 November 2022